

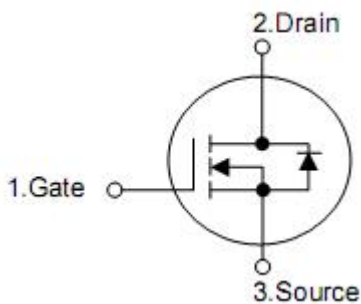
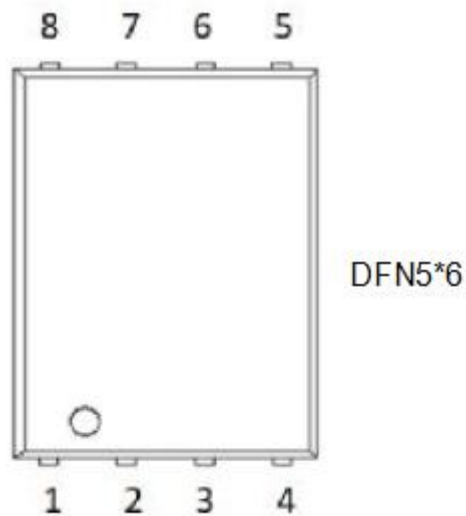
1. Features

- $R_{DS(on)}=2.6m\Omega(Typ.) @ V_{GS}=10V$
- Advanced Trench Technology
- Low Gate Charge
- High Current Capability
- RoHS and Halogen-Free Compliant

2. Description

- Power Management in Desktop Computer
- DC/DC Converters

3. Symbol



| Pin | Function |
|---------|----------|
| 4 | Gate |
| 5,6,7,8 | Drain |
| 1,2,3 | Source |

4. Ordering Information

| Part Number | Package | Brand |
|-------------|---------|-------|
| KCY3503S | DFN5*6 | KIA |

5. Absolute maximum ratings

| Parameter | Symbol | Rating | Units |
|---|----------------|-------------------|------------|
| Drain-source voltage | V_{DS} | 30 | V |
| Gate-source voltage | V_{GS} | ± 20 | V |
| Continuous drain current $V_{GS}@10V^{1,6}$ | I_D | $T_C=25^\circ C$ | 70 |
| | | $T_C=100^\circ C$ | 56 |
| Pulsed drain current ² | I_{DM} | 280 | A |
| Single pulse avalanche energy ³ | EAS | 115.2 | mJ |
| Avalanche current | I_{AS} | 48 | A |
| Total power dissipation ⁴ | P_D | 43.1 | W |
| Junction and storage temperature range | T_J, T_{STG} | -55 to 150 | $^\circ C$ |

6. Thermal Data

| Parameter | Symbol | Ratings | Units |
|---|-----------------|---------|--------------|
| Thermal resistance, junction-ambient ¹ | $R_{\theta JA}$ | 50 | $^\circ C/W$ |
| Thermal resistance, Junction-case ¹ | $R_{\theta Jc}$ | 2.9 | |

7. Electrical characteristics

(T_J=25°C, unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Units |
|---|---------------------|---|-----|------|------|-------|
| Drain-Source breakdown voltage | BV _{DSS} | V _{GS} =0V, I _D =-250μA | 30 | - | - | V |
| Drain-Source Leakage Current | I _{DSS} | V _{DS} =24V, V _{GS} =0V, T _J =25°C | - | - | 1 | μA |
| | | V _{DS} =24V, V _{GS} =0V, T _J =55°C | - | - | 5 | |
| Gate-source leakage current | I _{GSS} | V _{GS} =±20V, V _{DS} =0V | - | - | ±100 | nA |
| Gate threshold voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =250μA | 1.2 | 1.6 | 2.5 | V |
| Static drain-source on- resistance ² | R _{DS(on)} | V _{GS} =10V, I _D =15A | - | 2.6 | 3.8 | mΩ |
| | | V _{GS} =4.5V, I _D =15A | - | 3.6 | 4.8 | |
| Forward transconductance | g _{FS} | V _{DS} =5V, I _D =20A | - | 90 | - | S |
| Gate Resistance | R _g | V _{GS} =0V, V _{DS} =0V F=1MHZ | - | 1.6 | - | Ω |
| Total gate charge(4.5V) | Q _g | V _{DS} =15V, V _{GS} =10V I _D =20A | - | 20 | - | nC |
| Gate-source charge | Q _{gs} | | - | 12 | - | |
| Gate-drain charge | Q _{gd} | | - | 14.5 | - | |
| Turn-on delay time | t _{d(on)} | V _{DD} =15V, R _G =3.3Ω, V _{GS} =10V I _D =-20A | - | 11 | - | ns |
| Rise time | t _r | | - | 6 | - | |
| Turn-off delay time | t _{d(off)} | | - | 38 | - | |
| Fall time | t _f | | - | 11 | - | |
| Input capacitance | C _{iss} | V _{GS} =0V, V _{DS} =15V F=1.0MHZ | - | 3020 | - | pF |
| Output capacitance | C _{oss} | | - | 1570 | - | |
| Reverse transfer capacitance | C _{rss} | | - | 200 | - | |
| Diode characteristics | | | | | | |
| Continuous source current ^{1,6} | I _S | V _G =V _D =0V, Force current | - | - | 70 | A |
| Diode forward voltage ² | V _{SD} | V _{GS} =0V, I _S =1A, T _J =25°C | - | - | 1.4 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=48A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 70A.

8. Test circuits and waveforms

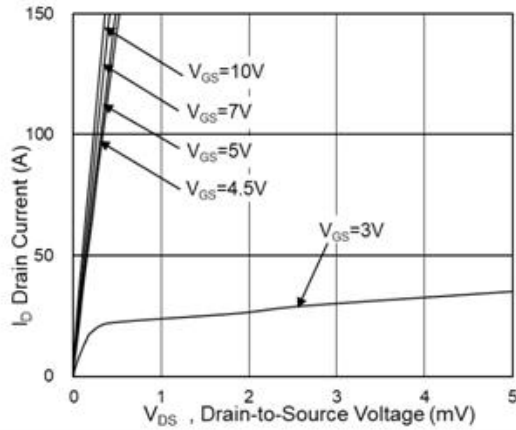


Fig.1 Typical Output Characteristics

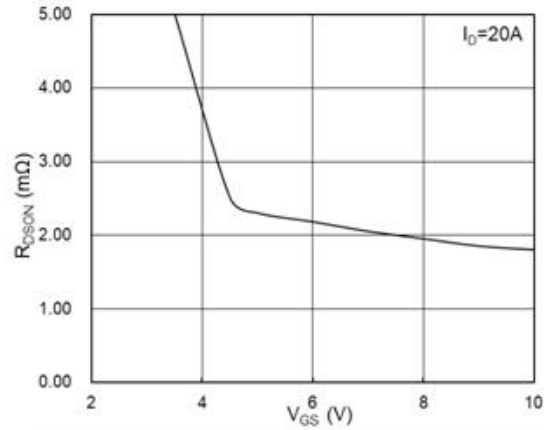


Fig.2 On-Resistance vs G-S Voltage

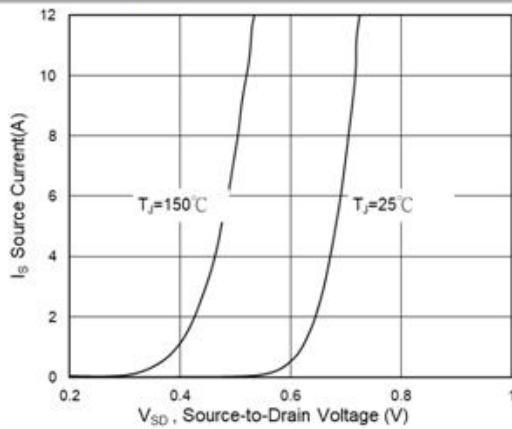


Fig.3 Source Drain Forward Characteristics

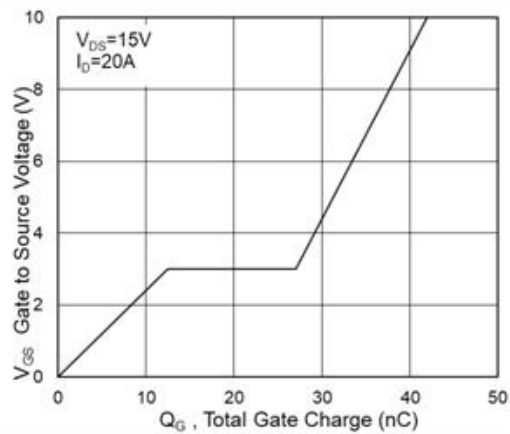


Fig.4 Gate-Charge Characteristics

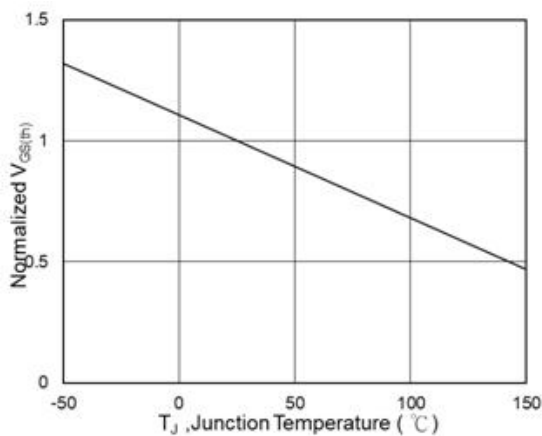


Fig.5 Normalized $V_{GS(th)}$ vs T_J

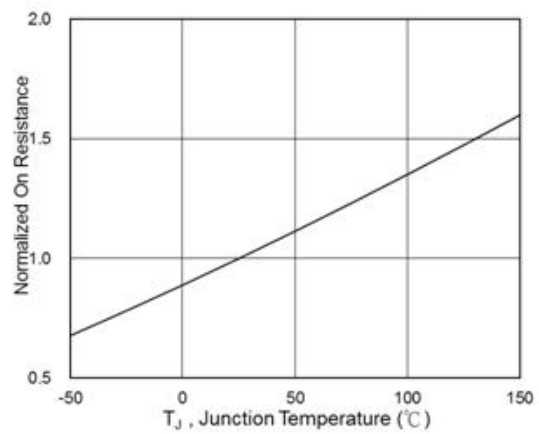


Fig.6 Normalized $R_{DS(on)}$ vs T_J

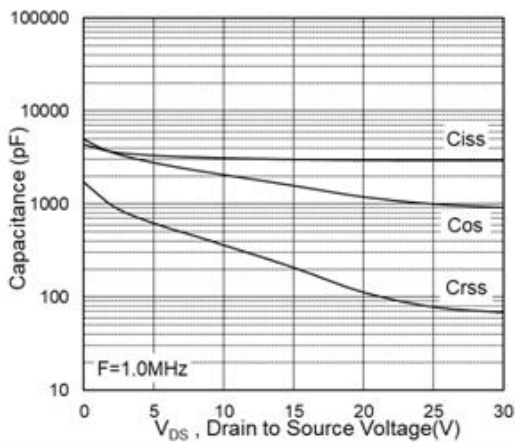


Fig.7 Capacitance

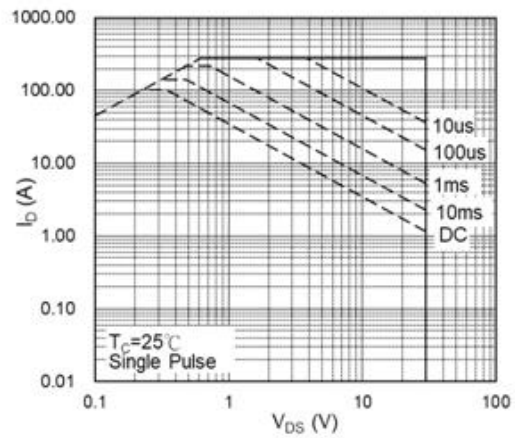


Fig.8 Safe Operating Area

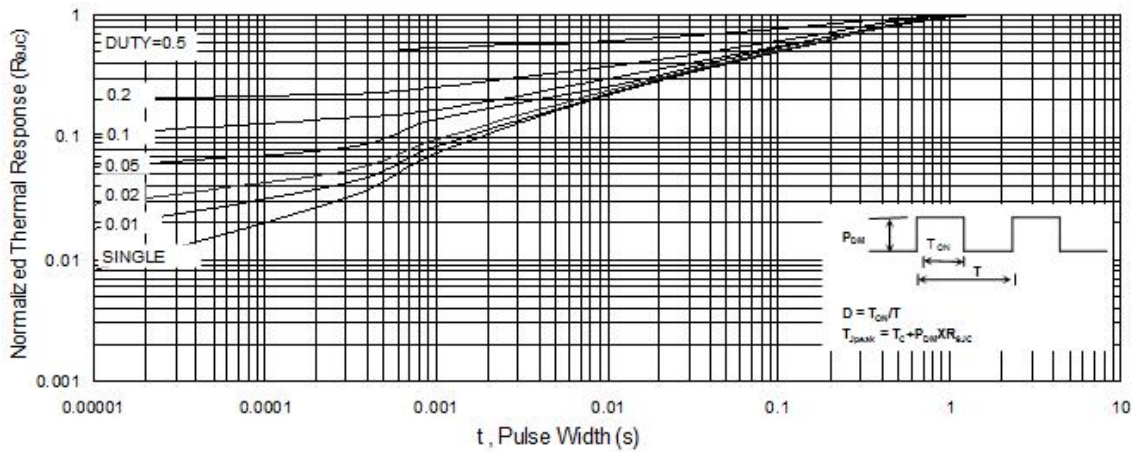


Fig.9 Normalized Maximum Transient Thermal Impedance

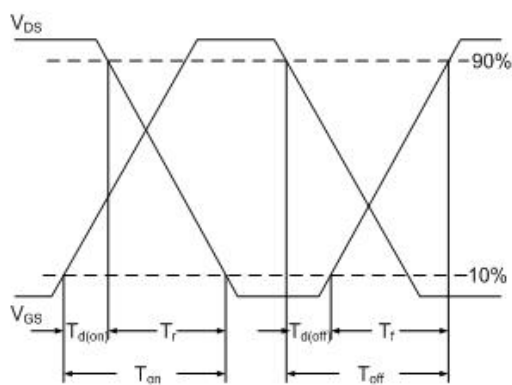


Fig.10 Switching Time Waveform

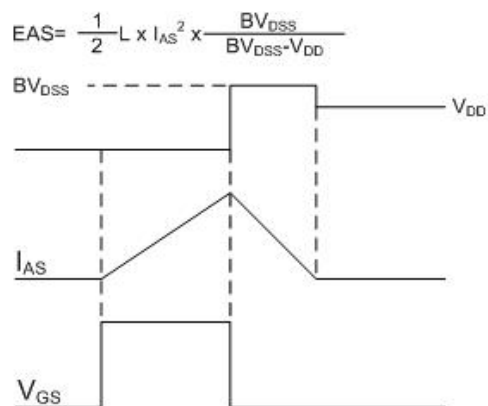


Fig.11 Unclamped Inductive Switching Waveform